Product Advisory (PA)

Subject: Package Change PTQFP-52 to TQFP-52
Publication Date: 7/1/2021
Effective Date: 7/1/2021
Revision Description:
Initial Release

Description of Change:
This notice is to advise customers that Renesas is discontinuing PTQFP-52 package and replacing with TQFP-52 as a result of the current assembly UTAC China discontinued the PTQFP-52 package. New package TQFP-52 will be assembled at Amkor Philippines. The material sets of the current and the new assembly locations are as shown in the below table. There will be no change in the moisture sensitive level.

Descriptions	PTQFP-52	TQFP-52
Die Attach	Henkel 2200D	Henkel 3230
Bond Wire	Copper wire	Copper wire
Mold Compound	EME-G700	EME-G700LY
Package Dimensions (LxWxT) Pitch	10 x 10 x 1.4mm 0.65mm	10 x 10 x 1.0mm 0.65mm
ePad Dimensions	4.5mm square	7.3mm square
Assembly	UTAC China	Amkor Philippines

Affected Product List: 8T33FS6221EPGI, 8T33FS6221EPGI8.

Reason for Change:
PTQFP-52 package is discontinued by the existing assembly UTAC China. No other assembly location offers this package.

Impact on Fit, Form, Function, Quality & Reliability:
The change will have no impact on the form, function, quality and reliability. Fit changes as stated above.

Product Identification:
New orderable part number 8T33FS6221ETGI, 8T33FS6221ETGI8.

Qualification Status: Refer Appendix A.
Sample Availability Date: 6/30/2021
Device Material Declaration: Available upon request.

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Renesas within 30 days of the publication date.

For additional information regarding this notice, please contact idt-pcn@lm.renesas.com

Appendix A - Qualification Results

Qual Vehicle: TQFP-52

Assembly Material: As shown in page 1

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Test Descriptions	Test Method	Test Results (Rej/SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130°C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
Ball Shear Test	JESD-B116	0/5	0/5	0/5
Physical Dimensions	JESD-B100	0/30	0/30	0/30
Solderability Test	MIL-STD-883 (Method 2003) J-STD-002D	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	-

**Tests were subjected to Preconditioning per JESD22-A113 prior to stress test*